

Data and signal line chokes

ACT1210R common-mode chokes, EIA 1210

Series/Type: **ACT1210R-101**

Date: July 2021

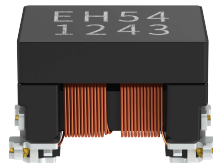
Rated voltage 80 V DC

Rated inductance 100 μ H

Rated current 150 mA

Construction

- Current compensation double choke
- Ferrite I core
- Winding enamel copper wire
- Winding welded to terminals



Features

- Operating temperature range $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Qualified to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

Function

- Suppression of asymmetrical interference coupled in on lines, whereas data signals can pass unaffectedly

Applications

- FlexRay bus system

Terminals

One-sided tinned terminals:

- Base material CuSn8
- Electro-plating Sn with Ni underlayer
- Lead-free tinned

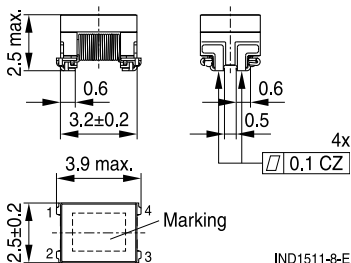
Marking

- Marking on component:
First line: L value ("E" = ACT1210R/100 μ H), production location ("H" = Heidenheim), two last digits of production order
Second line: date of manufacture (YWWD)

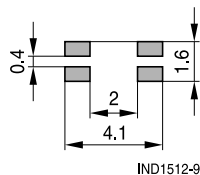
Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm $\varnothing$ reel
- Packing unit: 6000 pcs./reel

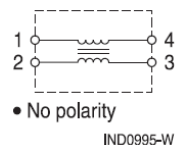
Dimensional drawing and pin configuration



Layout recommendation

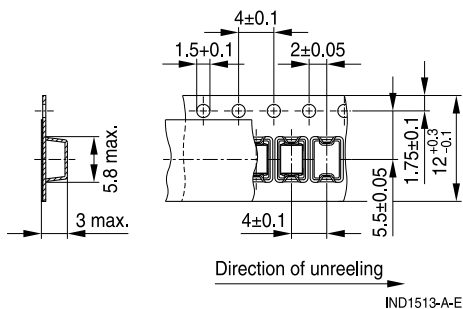


Circuit diagramm

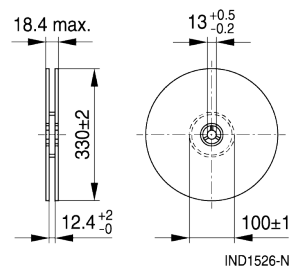


Taping and packing

Blister tape



Reel



Dimensions in mm

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ACT1210R-101

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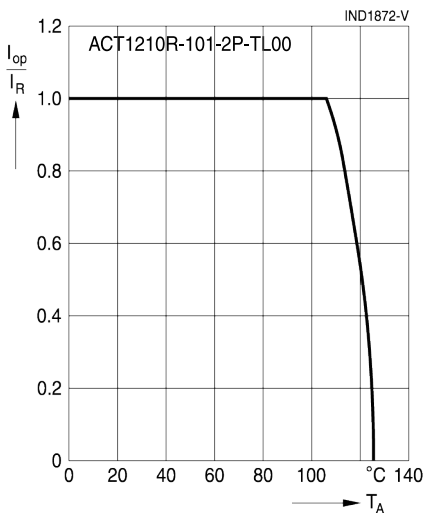
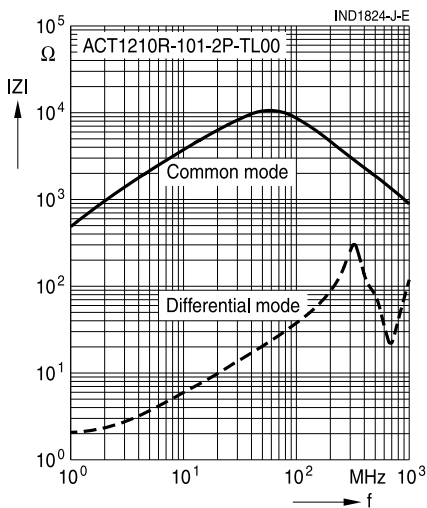
Technical data and measuring conditions

Rated Voltage V_R	80 V DC
Max. component temperature	+125 °C
Rated current I_R	Referred to 50 Hz and +20 °C
Rated inductance L_R	Measured with Keysight E4990A (or equivalent) at 100 kHz, 100 mV, +20 °C, inductance is specified in common-mode
Inductance tolerance	-30/+50% at +20 °C
DC resistance R_{max}	Measured at +20 °C, specified per winding
Insulation resistance $R_{iso,min}$	10 M Ω , measured at 50 V DC, +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: (245 $\pm$ 5) °C, (3 $\pm$ 0.3) s Wetting of soldering area $\geq$ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 30 s (as referenced in JEDEC J-STD-020D)
Climatic category	40/125/56 (to IEC 60068-1)
Operating temperature	-40 °C to +125 °C
Storage conditions (packaged)	-25 °C to +40 °C, $\leq$ 75% RH
Weight	Approx. 0.075 g

Characteristics and ordering codes

L_R μ H	I_R mA	$R_{iso,min}$ M Ω	$R_{DC,max}$ Ω	Internal code	Ordering code
100	150	10	1.1	B82786R0104N002	ACT1210R-101-2P-TL00

Impedance versus frequency (typical values) Current derating I_{op}/I_R
ACT1210R-101-2P-TL00 versus ambient temperature



Ferrites and accessories

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
 - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ceramics / Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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